

STN	Integrácia softvérového nástroja (FDI®) Časť 8: EDD až OPC-UA mapovanie	STN EN IEC 62769-8 18 4012
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Field device integration (FDI) - Part 8: EDD to OPC-UA Mapping

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/23

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**Field device integration (FDI®) - Part 8: EDD to OPC-UA
Mapping
(IEC 62769-8:2023)**

Intégration des appareils de terrain (FDI®) - Partie 8:
Mapping de l'EDD avec l'OPC-UA
(IEC 62769-8:2023)

Feldgeräteintegration (FDI®) - Teil 8: EDD zu OPC-UA
Mapping
(IEC 62769-8:2023)

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Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 62769-8:2023 (E)**European foreword**

The text of document 65E/851/CDV, future edition 1 of IEC 62769-8, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-8:2023.

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Annex ZA (normative)

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 62541-3	-	OPC Unified Architecture - Part 3: Address Space Model	EN IEC 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-5	-	OPC Unified Architecture - Part 5: Information Model	EN IEC 62541-5	-
IEC 62541-8	-	OPC Unified Architecture - Part 8: Data Access	EN IEC 62541-8	-
IEC 62541-9	2020	OPC Unified Architecture - Part 9: Alarms and Conditions	EN IEC 62541-9	2020
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	-	-
IEC 62769-1	-	Field Device Integration (FDI®) - Part 1: Overview	EN IEC 62769-1	-
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	EN IEC 62769-5	-
IEC 62769-6	-	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	EN IEC 62769-6	-
ISO/IEC 11179-6	-	Information technology - Metadata registries (MDR) - Part 6: Registration	-	-
OPC 30081	-	Process Automation Devices - PADIM	-	-
UN/CEFACT	-	UNECE Recommendation 20, Codes for Units of Measure Used in International Trade	-	-



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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 8: EDD to OPC-UA Mapping**

**Intégration des appareils de terrain (FDI®) –
Partie 8: Mapping de l'EDD avec l'OPC-UA**





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Edition 1.0 2023-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 8: EDD to OPC-UA Mapping**

**Intégration des appareils de terrain (FDI®) –
Partie 8: Mapping de l'EDD avec l'OPC-UA**

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Draft	Report on voting
65E/851/CDV	65E/909/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 8: EDD to OPC-UA Mapping

1 Scope

This part of IEC 62769 specifies how the internal view of a device model represented by the EDD can be transferred into an external view as an OPC-UA information model by mapping EDD constructs to OPC-UA objects.

2 Normative references

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IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

IEC 62541-9:2020, *OPC Unified Architecture – Part 9: Alarms and Conditions*

OPC 10000-17, *OPC Unified Architecture – Part 17: Alias Names*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

IEC 62541-100, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

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OPC 30081, *Process Automation Devices – PADIM*

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